

# United States 3D IC and 2.5D IC Packaging Market Report 2017

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## Abstracts

### Notes:

Sales, means the sales volume of 3D IC and 2.5D IC Packaging

Revenue, means the sales value of 3D IC and 2.5D IC Packaging

This report studies sales (consumption) of 3D IC and 2.5D IC Packaging in United States market, focuses on the top players, with sales, price, revenue and market share for each player, covering

Tezzaron

ASE Group

Amkor Technology

STATS ChipPAC Ltd.

Market Segment by States, covering

California

Texas

New York

Florida

Illinois

Split by product types, with sales, revenue, price, market share and growth rate of each type, can be divided into

3D wafer-level chip-scale packaging

3D TSV

2.5D

Split by applications, this report focuses on sales, market share and growth rate of 3D IC and 2.5D IC Packaging in each application, can be divided into

Consumer electronics

Telecommunication

Industrial sector

Automotive

Military and aerospace

Smart technologies

Medical devices

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